



3.3V PCI Express® 3.0 2-Lane Exchange Switch

Features

- → 8 Differential Channel (2-lane) Exchange
- → PCI Express[®] 3.0 performance, 8.0 Gbps
- → Bi-directional operation
- → Low Bit-to-Bit Skew: 10ps (between ± signals)
- → Low Crosstalk: -29dB @ 2.5GHz (5Gbps) -20dB @ 4.0GHz (8Gbps)
- → Low Insertion Loss: -1.1dB @ 2.5GHz (5Gbps) -1.45dB @ 4.0GHz (8Gbps)
- → V_{DD} Operating Range: 3.3V ±10%
- → Industrial Temperature Range: -40°C to 85°C
- → ESD Tolerance: 2kV HBM
- → Packaging (Pb-free & Green):
 - ^a 42-contact, TQFN (ZH42), 3.5x9mm.
 - □ 40-contact, TQFN (ZL40), 3x6mm.

Description

Diodes' PI3PCIE3442A is a differential exchange switch featuring pass-through pinout. It supports two full PCI Express® lanes operating at 8.0Gbps PCIe[®] 3.0 performance.

With the select control input low, Port A connects to Port B, and Port C connects to port D for an 8-channel differential passthough. When the select control input is high Port A connects to Port D, and Port B connects to Port C.

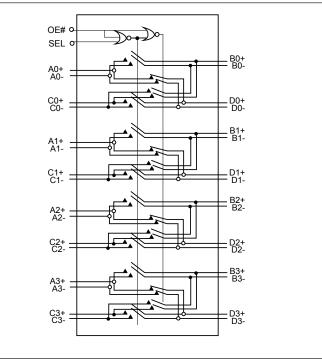
Application

Switching 4 lanes of DP1.2 from PC/Notebook/Tablet to Display monitor

Truth Table

Function	SEL	OE#
Ax = Bx $Cx = Dx$	0	0
Ax = Dx $Cx = Bx$	1	0
Ax, Bx, Cx, Dx = Hi-Z (disconnect)	х	1

Block Diagram



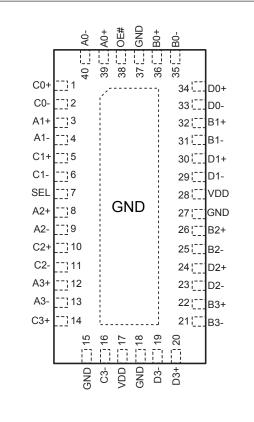




Pin Diagram 42-TQFN

A0+1 A02	40[41[0E# 40[VDD 39.7CND		B0+ B0-
C0+ 13	2 	36¦	D0+
C0- <u></u>]4 A1+ <u></u>]5	 	35 <u> </u>	D0- B1+
A16		33!	B1-
C1+ <u></u> 17		32¦	D1+
C1	GND	31[D1-
SEL <u>1</u> 9 A2+110		30¦ 29¦	VDD B2+
A2+ <u>11</u> 10 A2- <u>11</u> 11		28;	B2-
$A2^{-}$ 112		27¦	D2+
C2113		26	D2-
A3+14		25	B3+
A3115		24'	B3-
C3+16		23	D3+
C3117		22;	D3-
			I

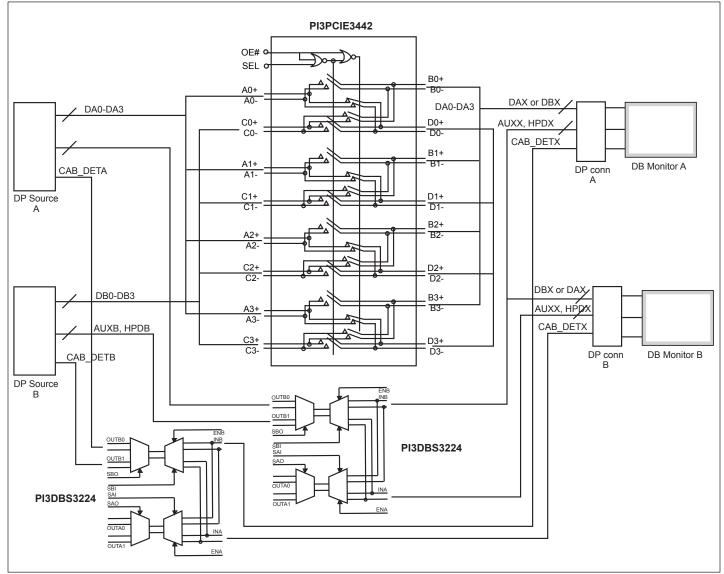
Pin Diagram 40-TQFN







Application Diagram



Generic 2 x 2 DP1.2 Switching Using PI3PCIE3442A (3x6mm 40 pad QFN)





Pin Description (42-TQFN)

Pin #	Pin Name	I/O	Description
1	A0+	I/O	Signal I/O, Channel 0, Port A
2	A0-		
5	A1+	I/O	Signal I/O, Channel 1, Port A
6	A1-		
10	A2+	I/O	Signal I/O, Channel 2, Port A
11	A2-		
14	A3+	I/O	Signal I/O, Channel 3, Port A
15	A3-		
38	B0+	I/O	Signal I/O, Channel 0, Port B
37	B0-		
34	B1+	I/O	Signal I/O, Channel 1, Port B
33	B1-		
29	B2+	I/O	Signal I/O, Channel 2, Port B
28	B2-		
25	B3+	I/O	Signal I/O, Channel 3, Port B
24	B3-		
3	C0+	I/O	Signal I/O, Channel 0, Port C
4	C0-		
7	C1+	I/O	Signal I/O, Channel 1, Port C
8	C1-		
12	C2+	I/O	Signal I/O, Channel 2, Port C
13	C2-		
16	C3+	I/O	Signal I/O, Channel 3, Port C
17	C3-		
36	D0+	I/O	Signal I/O, Channel 0, Port D
35	D0-		
32	D1+	I/O	Signal I/O, Channel 1, Port D
31	D1-		
27	D2+	I/O	Signal I/O, Channel 2, Port D
26	D2-		
23	D3+	I/O	Signal I/O, Channel 3, Port D
22	D3-		
41	OE#	Ι	Output Enable, active low. When OE# = 0 the device I/O is enabled. When OE#=1, all I/O are high impedance
9	SEL	Ι	Operation mode Select (when SEL=0: $A \rightarrow B$, $C \rightarrow D$, when SEL=1: $A \rightarrow D$, $C \rightarrow B$)
18, 20, 30, 40, 42	V _{DD}	Pwr	3.3V ±10% Positive Supply Voltage
19, 21, 39, Center Pad	GND	Pwr	Power ground





Pin Description (40-TQFN)

Pin #	Pin Name	I/O	Description
39	A0+	I/O	Signal I/O, Channel 0, Port A
40	A0-		
3	A1+	I/O	Signal I/O, Channel 1, Port A
4	A1-		
8	A2+	I/O	Signal I/O, Channel 2, Port A
9	A2-		
12	A3+	I/O	Signal I/O, Channel 3, Port A
13	A3-		
36	B0+	I/O	Signal I/O, Channel 0, Port B
35	В0-		
32	B1+	I/O	Signal I/O, Channel 1, Port B
31	B1-		
26	B2+	I/O	Signal I/O, Channel 2, Port B
25	B2-		
22	B3+	I/O	Signal I/O, Channel 3, Port B
21	B3-		
1	C0+	I/O	Signal I/O, Channel 0, Port C
2	C0-		
5	C1+	I/O	Signal I/O, Channel 1, Port C
6	C1-		
10	C2+	I/O	Signal I/O, Channel 2, Port C
11	C2-		
14	C3+	I/O	Signal I/O, Channel 3, Port C
16	C3-		
34	D0+	I/O	Signal I/O, Channel 0, Port D
33	D0-		
30	D1+	I/O	Signal I/O, Channel 1, Port D
29	D1-		
24	D2+	I/O	Signal I/O, Channel 2, Port D
23	D2-		
20	D3+	I/O	Signal I/O, Channel 3, Port D
19	D3-		
38	OE#	Ι	Output Enable, active low. When OE# = 0 the device I/O is enabled. When OE#=1, all I/O are high impedance
7	SEL	Ι	Operation mode Select (when SEL=0: $A \rightarrow B$, $C \rightarrow D$, when SEL=1: $A \rightarrow D$, $C \rightarrow B$)
17, 28	V _{DD}	Pwr	3.3V ±10% Positive Supply Voltage
15, 18, 27, 37, Center Pad	GND	Pwr	Power ground





Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	65°C to +150°C
Supply Voltage to Ground Potential	-0.5V to +3.7V
DC Input Voltage	– $0.5V$ to V_{DD}
DC Output Current	
Power Dissipation	0.5W
Junction Temperature	125°C

Note: Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Electrical Characteristics Recommended Operating Conditions

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
V _{DD}	3.3V Power Supply		3.0	3.3	3.6	V
I _{DD}	Total current from V _{DD} 3.3V supply	SEL and OE# at OV or V_DD			300	μΑ
T _A	Operating temperature range		-40		85	°C

DC Electrical Characteristics for Switching over Operating Range

Parameters	Description	Test Conditions ⁽¹⁾	Min.	Typ. ⁽¹⁾	Max.	Units
V _{IH}	Input HIGH Voltage	Guaranteed HIGH level	$0.65 \mathrm{x} \mathrm{V}_\mathrm{DD}$			
V _{IL}	Input LOW Voltage	Guaranteed LOW level	-0.5		$0.35 \mathrm{~x~V_{DD}}$	V
V _{IK}	Clamp Diode Voltage	$V_{DD} = Max., I_{IN} = -18mA$		-0.7	-1.2	
I _{IH}	Input HIGH Current, SEL	$V_{DD} = Max., V_{IN} = V_{DD}$	-10		+10	
I _{IL}	Input LOW Current, SEL	V _{DD} = Max., V _{IN} = GND	-10		+10	μΑ
IIH	Input HIGH Current, A_X , B_X , C_{X_1} D_X	$V_{DD} = Max., V_{IN} = 1.8V$	-10		+10	μA
IIL	Input LOW Current, A _X , B _X , C _X , D _X	$V_{DD} = Max., V_{IN} = 0V$	-10		+10	F

Note:

1. Typical values are at VDD = 3.3V, TA = 25°C ambient and maximum loading.

Switching Characteristics

Parameters	Description	Test Conditions	Min.	Тур.	Max.	Units
t _{PZH} , t _{PZL}	Line Enable Time - SEL to A_N , B_N , C_N , D_N		0.5		45	
t _{PHZ} , t _{PLZ}	Line Disable Time - SEL to A_N , B_N , C_N , D_N		0.5		25	ns
t _{b-b}	Bit-to-bit skew within the same differential pair				10	
t _{ch-ch}	Channel-to-channel skew				20	ps





Dynamic Electrical Characteristics

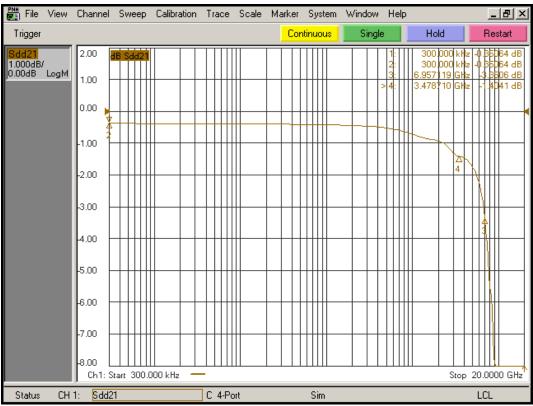
Parameter	Description	Test Conditions	Min.	Typ. ⁽¹⁾	Max.	Units
		f=1.2GHz		-0.8	-1.0	
	D'fferential Learnting Land	f=2.5GHz		-1.0	-1.2	
DDIL	Differential Insertion Loss	f=4.0GHz		-1.3	-1.9	dB
	$(V_{\rm IN} = -10 dBm, DC = 0V)$	f=5.0GHz		-1.8	-2.6	
		f=7.5GHz		-4.5	-5.6	
DDIL	Differential Off Isolation	f= 4.0GHz		-19		dB
		f= 0 to 2.8GHz		-26		
DDRL	DDRL Differential Return Loss	f= 2.8 to 5.0GHz		-14		dB
		f= 5.0 to 8.0GHz		-7.5		
		f= 0 to 2.8GHz		-26		
DDNEXT	Near End Crosstalk	f= 2.8 to 5.0GHz		-20		dB
		f= 5.0 to 8.0GHz		-16		
		Insertion loss 1.5dB, V _{IN} =0.623Vpp, DC=0V		4.0		
V _{I F} Max Signal Frequency Range	M C IF F	Insertion loss 1.5dB, V _{IN} =0.623Vpp, DC=0.9V		4.0		CIL
	Max Signal Frequency Range	Insertion loss 3dB, V _{IN} =0.623Vpp, DC=0V		8.0		GHz
		Insertion loss 3dB, V _{IN} =0.623Vpp, DC=0.9V		8.0		
BW	-3dB Bandwidth			6.5		GHz

Notes:

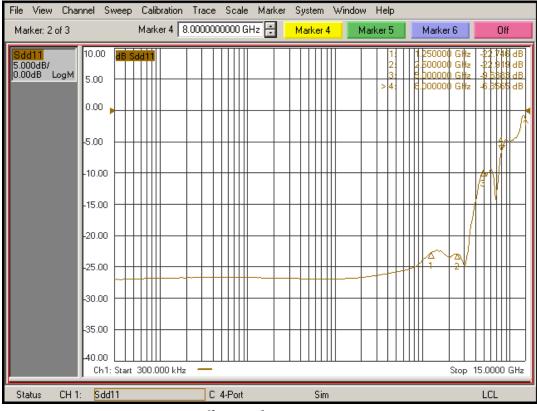
1. Guaranteed by design. Typical values are at $\rm V_{DD}$ = 3.3V , $\rm T_A$ = 25°C ambient and maximum loading.







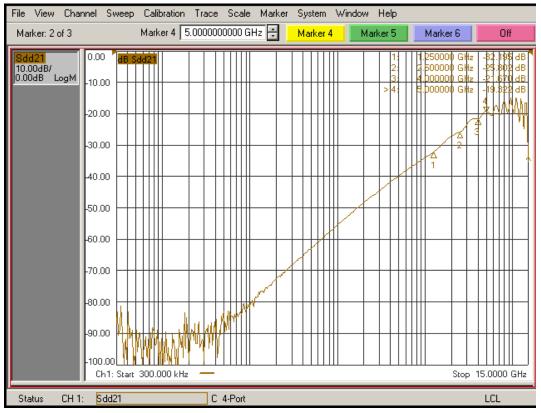
Differential Insertion Loss



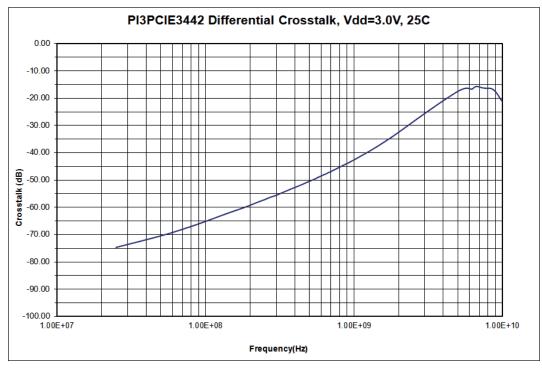
Differential Return Loss







Differential Off Isolation

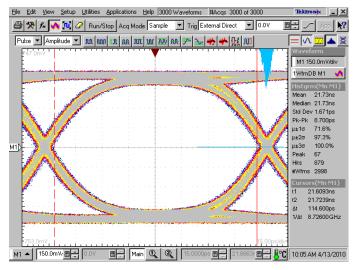


Differential Crosstalk

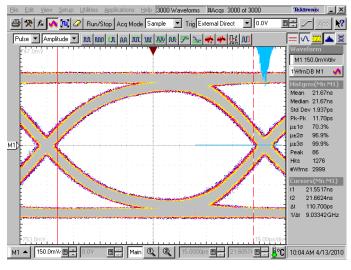


A product Line of Diodes Incorporated

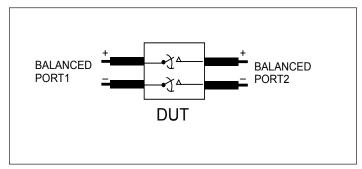
PI3PCIE3442A



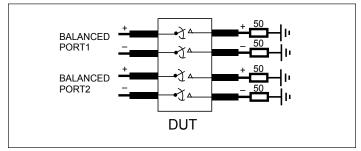
8.0 Gbps RX signal eye without PI3PCIE3442A



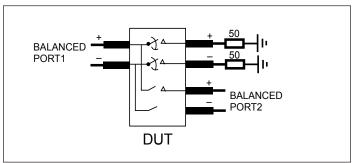
8.0 Gbps RX signal eye with PI3PCIE3442A



Differential Insertion Loss and Return Test Circuit



Differential Near End Xtalk Test Circuit

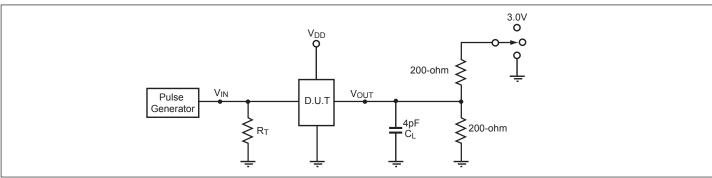


Differential Off Isolation Test Circuit





Test Circuit for Electrical Characteristics⁽¹⁻⁵⁾



Notes:

1. C_L = Load capacitance: includes jig and probe capacitance.

2. R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator

3.Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control. output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

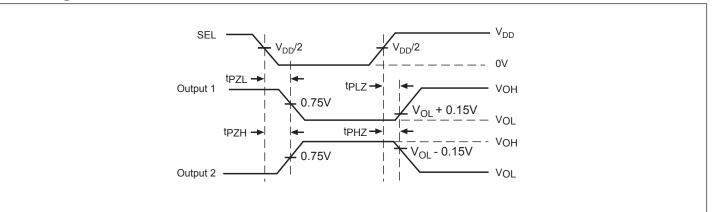
4. All input impulses are supplied by generators having the following characteristics: PRR \leq MHz, $Z_{O} = 50\Omega$, $t_{R} \leq 2.5$ ns, $t_{F} \leq 2.5$ ns.

5. The outputs are measured one at a time with one transition per measurement.

Switch Positions

Test	Switch
t_{PLZ}, t_{PZL}	3.0V
t _{PHZ} , t _{PZH}	GND
Prop Delay	Open

Switching Waveforms



Voltage Waveforms Enable and Disable Times





Part Marking Information

ZH Package

ZL Package

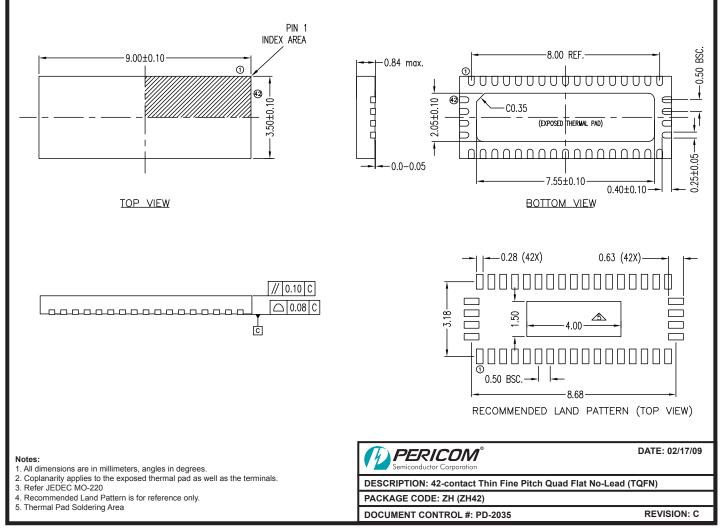


YY : Year WW : Workweek 1st X: Assembly Code 2nd X: Fab Code

PI3PCIE 3442AZLE **OYYWWXX**

YY : Year WW : Workweek 1st X: Assembly Code 2nd X: Fab Code

Packaging Mechanical: 42-Contact TQFN (3.5x9mm)

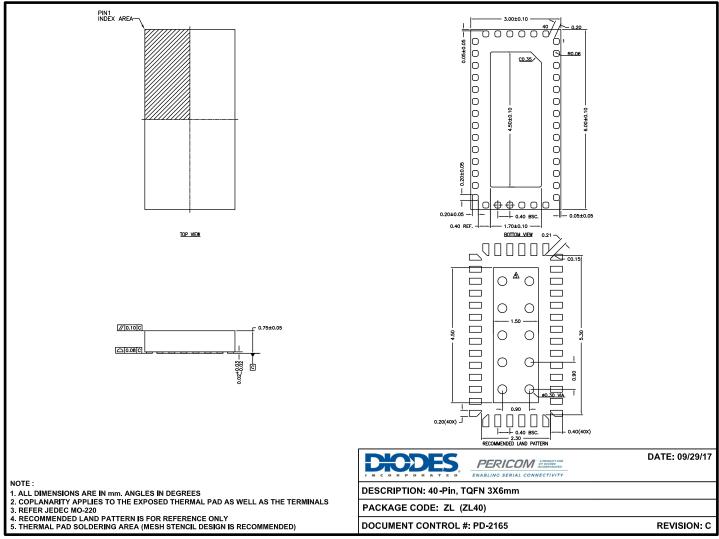








Packaging Mechanical: 40-Contact TQFN (3x6mm)



17-0681

For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

Ordering Information

Ordering Code	Package Code	Package Description
PI3PCIE3442AZHEX	ZH	42-contact, Thin Fine Pitch Quad Flat No-Lead (TQFN)
PI3PCIE3442AZLEX	ZL	40-contact, 3 x 6mm (TQFN)

Notes:

· Thermal characteristics can be found on the company web site at www.diodes.com/design/support/packaging/

• E = Pb-free and Green

• X suffix = Tape/Reel





IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND. EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.

Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application. Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the

failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2016, Diodes Incorporated www.diodes.com

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for PCI Interface IC category:

Click to view products by Diodes Incorporated manufacturer:

Other Similar products are found below :

PEX8508-AC25BIG CA91L8260B-100CE PI7C9X119SLFDE PM8561B-F3EI PI7C9X111SLBFDE-2017 PEX8747-CA80FBC G SS17-0B00-00 SS14-0B00-00 PI7C9X2G304ELQZXAEX SS19-0B00-00 SS18-0B00-00 PEX8664-AA50RBC G PEX8632-BB50RBC G PEX8648-BB50RBC G PEX8680-AA50RBC G SS16-0B00-00 PEX8648-BB50RBI G PEX8606-BA50BIG PI7C9X110BNBE PI7C9X110BNBE 89HPES3T3ZBBCGI PCA9617ADPJ XIO2213BIZAY XIO2001PNP XIO2201IPNP XIO2213BZAY PI7C8150BMAE PI7C9X111SLBFDEX 89H32NT24AG2ZCHLG 89H32T8G2ZCBLG 89HPES16T4AG2ALGI 89HPES12NT3ZBBCG 89H32T8G2ZCBLGI 89H32NT24BG2ZCHLG CA91L862A-50ILV 89HPES8T5AZBBCG PI7C8150BNDIE PI7C9X2G308GPANJE PI7C8152BMAE 89H32NT8AG2ZCHLGI 89H48H12G2ZDBLG 89HPES24T6G2ZCALGI 89H32NT24AG2ZBHLGI 89HPES4T4G2ZCALGI 89HPES10T4G2ZBBCG 89HPES12N3AZGBCGI 89HPES8T5AZBBCGI PEX8764-AB80BI G PI7C8150BMAIE 89HPES4T4G2ZCALGI